IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				under both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mi	ials and Mfg Information				
Supplier Inforn	nation															
Company name* Compa				ompany unique ID U			Unique ID Authority					Response Date*				
nsemi							I					2023-06-	2023-06-08			
Contact Name			Title - Contact			P	Phone - Contact*					Email - Contact*				
Product-Env-Stewa	ards	Product Enviro Compliance			1	NA					Product-Env-Stewards@onsemi.com					
uthorized Represe	Title - Representative			Phone - Representative*				Email - Representative*								
Product-Env-Stewa	ards	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com							
Requesto	r Item Number Mfr Item		tem Number Mfr Item Name				Effective Da	fective Date Version		Manufacturing Site PH1			Weight* UOM 21.81 mg		UOM	Unit Type
				3.3V 250MHz LV Fanout Buffer Fa	Hz LVCMOS/LVTTL Low Skew fer Family		2023-06-08 P		2			mg			Each	
Ianufacturing	Proccess Informatio	n														
Terminal	al Plating / Grid Array Material		Terminal Base Alloy		J-STD-020 MSL Rating		Peak Process Body Tempe		ody Temperatu	ture Max Time at Peak		Temperati	Temperature Number of Reflow Cycles		les	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1		1	260		C		30 seco		secono	ds 3	3		
Comments												-				
vel 1 - maximum t	ime at peak temperature	during sol	dering is 10-3	0 seconds		·	·		·		·					
or more informati	on regarding material co	nposition	please refer to	page 3	·	·	·		·		·					

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.84	mg	Supplier	Silicon (Si)	7440-21-3		0.84	mg
Die Attach	0.31	mg		Epoxy resin	proprietary data		0.031	mg
			Supplier	Ethylene dimethacrylate	97-90-5		0.0155	mg
			Supplier	Silver (Ag)	7440-22-4		0.248	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.0155	mg
Lead Frame	10.38	mg	Supplier	Zinc (Zn)	7440-66-6		0.0125	mg
			Supplier	Iron (Fe)	7439-89-6		0.2439	mg
			Supplier	Copper (Cu)	7440-50-8		10.1205	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0031	mg
Mold Compound-Black	10.1	mg		Epoxy resin	proprietary data		0.7575	mg
			Supplier	Phenolic Resin	Proprietary Data		0.2525	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.7575	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0505	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		8.282	mg
Plating	0.11	mg	Supplier	Palladium (Pd)	7440-05-3		0.01	mg
			В	Nickel (Ni)	7440-02-0		0.0989	mg
			Supplier	Gold (Au)	7440-57-5		0.0011	mg
Wire Bond - Au	0.07	mg	Supplier	Gold (Au)	7440-57-5		0.07	mg